Molding Type Module IGBT, 2 in 1 Package, 1200 V and 100 A

Dual INT-A-PAK

FEATURES

- NPT IGBT technology
- 10 µs short circuit capability
- Low switching losses
- Rugged with ultrafast performance
- $V_{CE(on)}$ with positive temperature coefficient
- Low inductance case
- Fast and soft reverse recovery antiparallel FWD
- Isolated copper baseplate using DCB (Direct Copper Bonding) technology
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

RoHS COMPLIANT

TYPICAL APPLICATIONS

- Switching mode power supplies
- Inductive heating
- Electronic welder

DESCRIPTION

Vishay's IGBT power module provides ultrafast switching speed as well as short circuit ruggedness. It is designed for applications such as electronic welders and inductive heating.

PRIMARY CHARACTERISTICS	
V_{CES}	1200 V
I_C at T_C = 80 °C	100 A
$V_{CE(on)}$ (typical) at I_C = 100 A, 25 °C	3.10 V
Speed	8 kHz to 30 kHz
Package	Dual INT-A-PAK
Circuit configuration	Half bridge

ABSOLUTE MAXIMUM RATINGS (T_C = 25 °C unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS
Collector to emitter voltage	V_{CES}		1200	V
Gate to emitter voltage	V_{GES}		± 20	
Collector current	I_C	T_C = 25 °C	200	A
		T_C = 80 °C	100	
Pulsed collector current	I_{CM} (1)	t_p = 1 ms	200	
Diode continuous forward current	I_F		100	
Diode maximum forward current	I_{FM}(1)		200	
Maximum power dissipation	P_D	T_J = 150 °C	1136	W
Isolation voltage	V_{ISOL}	f = 50 Hz, t = 1 min	2500	V

Note

(1) Repetitive rating: pulse width limited by maximum junction temperature

IGBT ELECTRICAL SPECIFICATIONS (T_C = 25 °C unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Collector to emitter breakdown voltage	$V_{(BR)CES}$	T_J = 25 °C	1200	-	-	V
Collector to emitter voltage	$V_{CE(on)}$	V_{GE} = 15 V, I_C = 100 A, T_J = 25 °C	-	3.10	3.60	
		V_{GE} = 15 V, I_C = 100 A, T_J = 125 °C	-	3.45	-	
Gate to emitter threshold voltage	$V_{GE(th)}$	V_{CE} = V_{GE}, I_C = 1 mA, T_J = 25 °C	4.4	4.9	6.0	
Zero gate voltage collector current	I_{CES}	V_{CE} = V_{CES}, V_{GE} = 0 V, T_J = 25 °C	-	-	5.0	mA
Gate to emitter leakage current	I_{GES}	V_{GE} = V_{GES}, V_{CE} = 0 V, T_J = 25 °C	-	-	400	nA

SWITCHING CHARACTERISTICS

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Turn-on delay time	$t_{d(on)}$	V_{CC} = 600 V, I_C = 100 A, R_g = 5.6 Ω, V_{GE} = ± 15 V, L = 200 nH, T_J = 25 °C	-	300	-	ns
Rise time	t_r		-	64	-	
Turn-off delay time	$t_{d(off)}$		-	340	-	
Fall time	t_f		-	105	-	
Turn-on switching loss	E_{on}		-	4.76	-	mJ
Turn-off switching loss	E_{off}		-	4.25	-	
Turn-on delay time	$t_{d(on)}$	V_{CC} = 600 V, I_C = 100 A, R_g = 5.6 Ω, V_{GE} = ± 15 V, L = 200 nH, T_J = 125 °C	-	320	-	ns
Rise time	t_r		-	65	-	
Turn-off delay time	$t_{d(off)}$		-	350	-	
Fall time	t_f		-	132	-	
Turn-on switching loss	E_{on}		-	7.20	-	mJ
Turn-off switching loss	E_{off}		-	5.50	-	
Short circuit withstand time	t_{SC}	T_J = 125 °C	-	-	10	µs
Input capacitance	C_{ies}	V_{GE} = 0 V, V_{CE} = 20 V, f = 1.0 MHz	-	8.45	-	nF
Output capacitance	C_{oes}		-	0.76	-	
Reverse transfer capacitance	C_{res}		-	0.31	-	
SC data	I_{SC}	$t_p \leq 10$ µs, V_{GE} = ± 15 V, V_{CC} = 600 V, $V_{CEM} \leq 1200$ V, T_J = 25 °C	-	900	-	
Internal gate resistance	R_{GINT}		-	2.4	-	Ω
Stray inductance	L_{CE}		-	-	18	nH
Module lead resistance, terminal to chip	$R_{CC'+EE'}$		-	0.32	-	mΩ

DIODE ELECTRICAL SPECIFICATIONS

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
Diode forward voltage	V_F	I_F = 100 A	T_C = 25 °C	-	1.82	2.22	V
			T_C = 125 °C	-	1.95	-	
Diode reverse recovery charge	Q_{rr}	I_F = 100 A, V_R = 600 V, dI_F/dt = -1900 A/µs, V_{GE} = -15 V	T_C = 25 °C	-	5.4	-	µC
			T_C = 125 °C	-	11.2	-	
Diode peak reverse recovery current	I_{rr}		T_C = 25 °C	-	81	-	A
			T_C = 125 °C	-	101	-	
Diode reverse recovery energy	E_{rec}		T_C = 25 °C	-	3.54	-	mJ
			T_C = 125 °C	-	6.57	-	

THERMAL AND MECHANICAL SPECIFICATIONS

PARAMETER		SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Operating junction temperature range		T_J		-40	-	150	°C
Storage temperature range		T_{Stg}		-40	-	125	
Junction to case	IGBT	R_{thJC}		-	-	0.141	°C/W
	Diode			-	-	0.225	
Case to sink		R_{thCS}	Conductive grease applied	-	0.035	-	
Mounting torque			Power terminal screw: M6	2.5 to 5.0			Nm
			Mounting screw: M6	3.0 to 6.0			
Weight				300			g

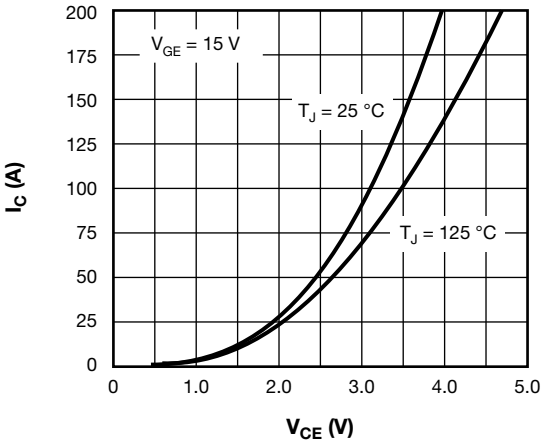


Fig. 1 - IGBT Typical Output Characteristics

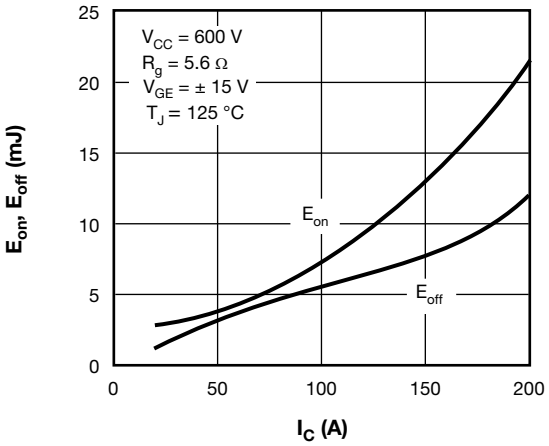


Fig. 3 - Switching Loss vs. I_C

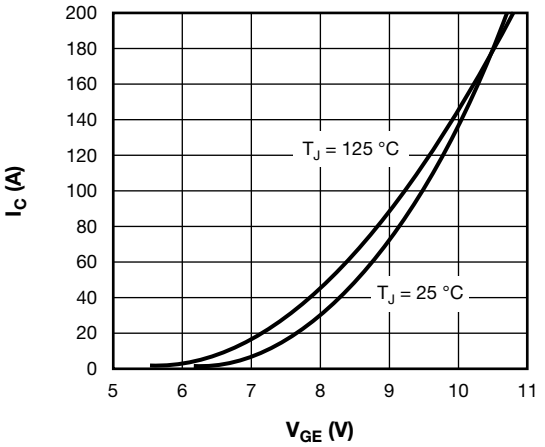


Fig. 2 - IGBT Typical Transfer Characteristics

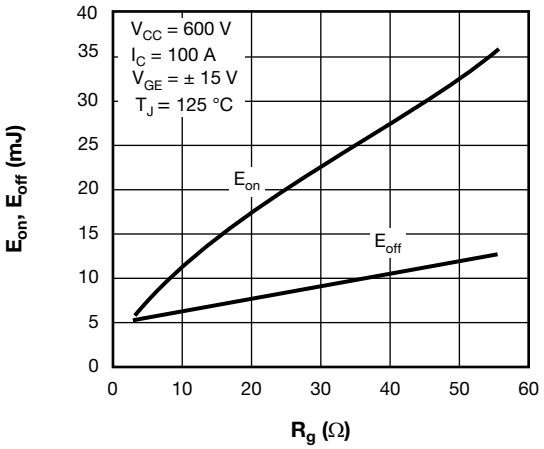


Fig. 4 - IGBT Switching Loss vs. R_g

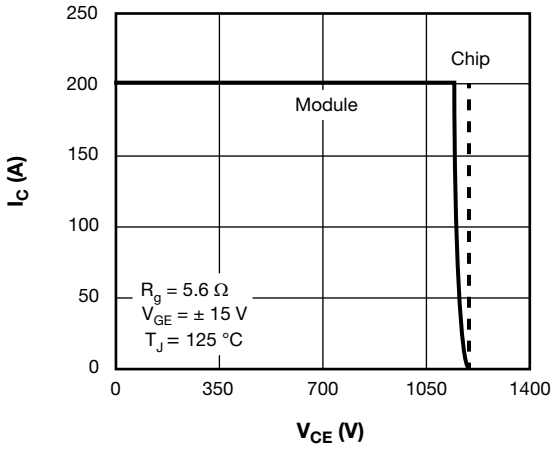


Fig. 5 - RBSOA

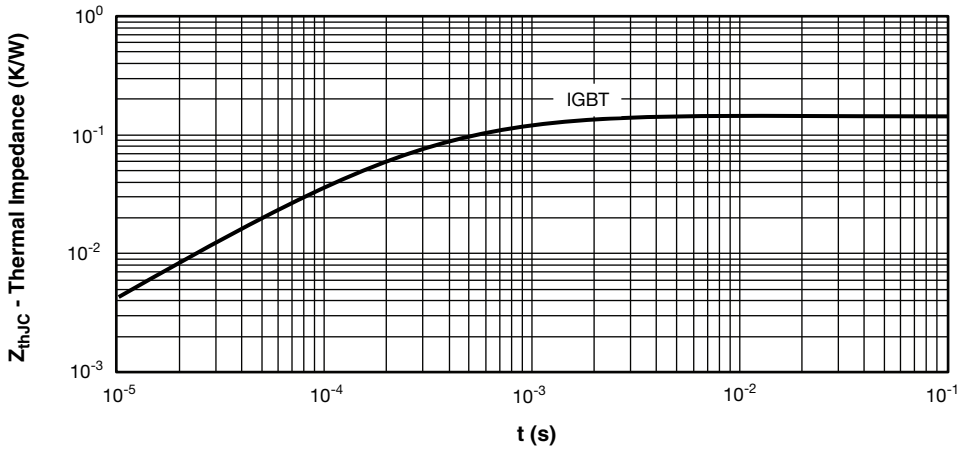


Fig. 6 - IGBT Transient Thermal Impedance

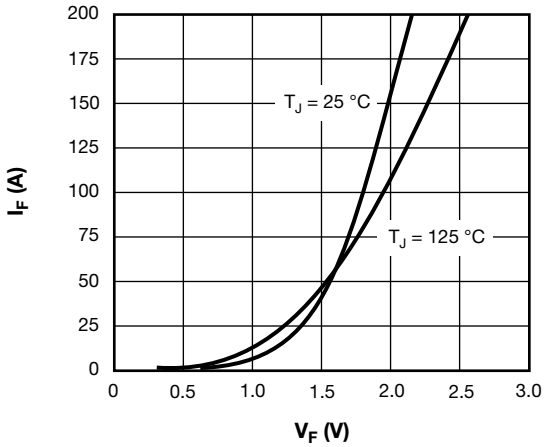


Fig. 7 - Diode Typical Forward Characteristics

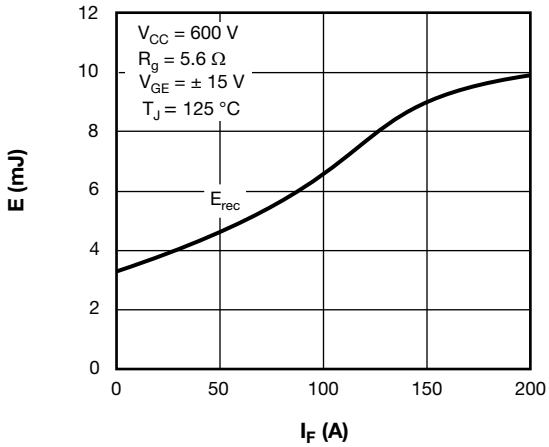


Fig. 8 - Diode Switching Loss vs. I_F

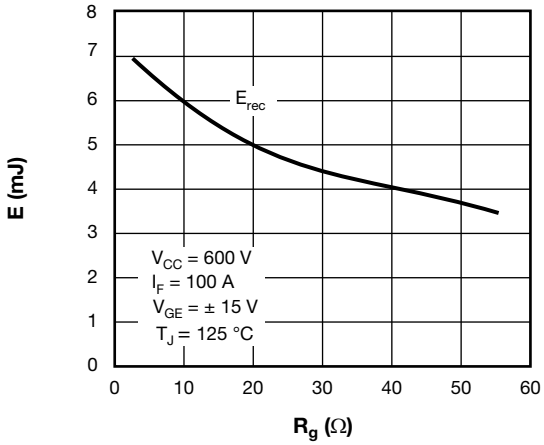


Fig. 9 - Diode Switching Loss vs. R_g

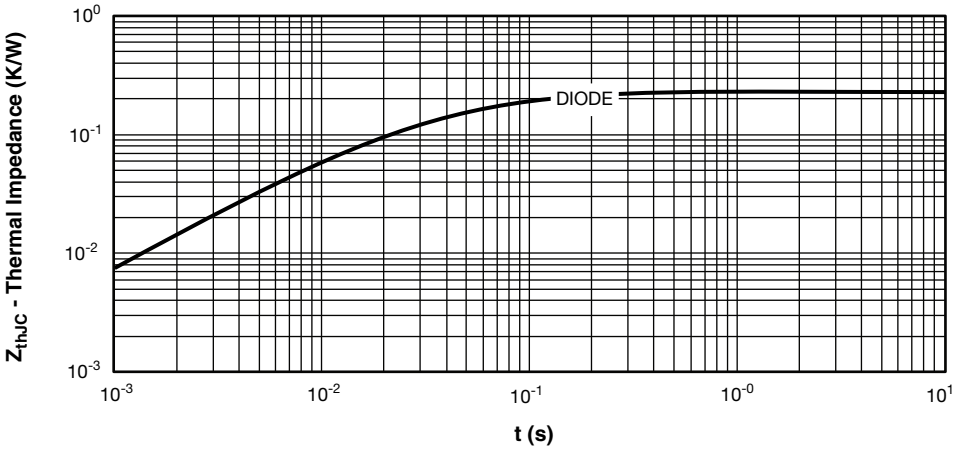
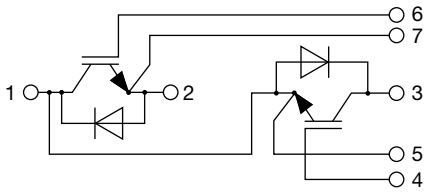


Fig. 10 - Diode Transient Thermal Impedance

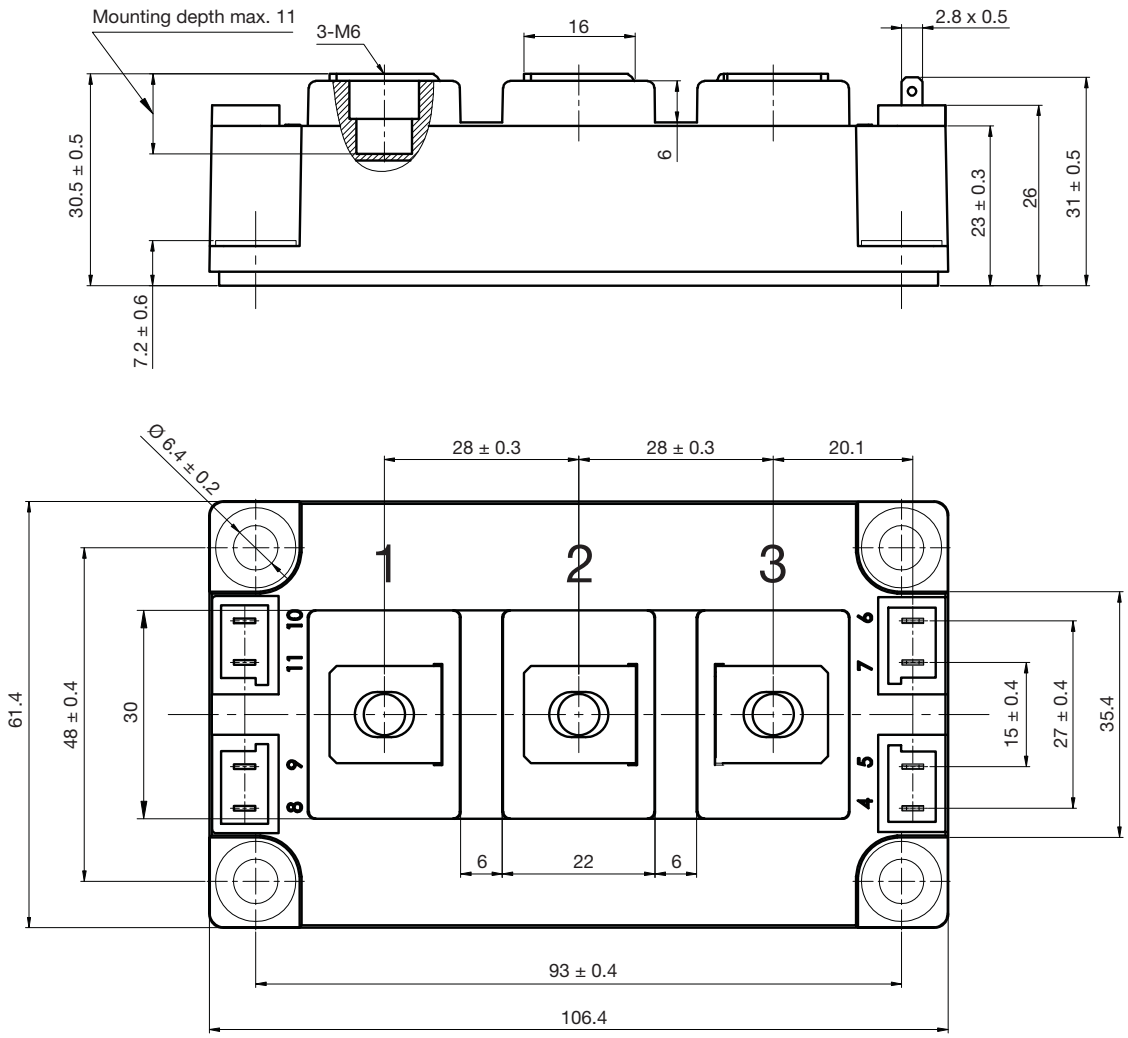
CIRCUIT CONFIGURATION



LINKS TO RELATED DOCUMENTS	
Dimensions	www.vishay.com/doc?95525

Double INT-A-PAK

DIMENSIONS in millimeters (inches)



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